## In the Specification:

Please add a new section directly before "Technical Field" as follows:

## CROSS-REFERENCE TO RELATED APPLICATION

This application is a divisional application of U.S. Patent Application No. 10/228,906, entitled "MICROELECTRONIC DEVICES WITH IMPROVED HEAT DISSIPATION AND METHODS FOR COOLING MICROELECTRONIC DEVICES," filed August 27, 2002, now U.S. Patent No. \_\_\_\_\_\_, issued \_\_\_\_\_\_, which is incorporated herein by reference in its entirety.